



Integrated Device Technology, Inc.  
2975 Stender Way, Santa Clara, CA - 95054

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0301-02**                      DATE: 4/2/2003  
 Product Affected:  
 IDT72V2103, IDT72V2113, IDT72V36100, IDT72V36110  
 IDT72V295, IDT72V2105, IDT72V2101, IDT72V2111  
 Date Effective: 7/2/2003

MEANS OF DISTINGUISHING CHANGED DEVICES:  
 Product Mark  
 Back Mark                      Please see Description section below  
 Date Code                      for details  
 Other

Contact: Dasharath Patel  
 Title: Quality Assurance Manager                      Attachment:  Yes                       No  
 Phone #: (408) 330-1488  
 Fax #: (408) 330-1450                      Samples: Available now  
 E-mail: [Dasharath.Patel@idt.com](mailto:Dasharath.Patel@idt.com)

**DESCRIPTION AND PURPOSE OF CHANGE:**

Die Technology                      Die shrink and process change from CEMOS 8 to CEMOS 11.5  
 Wafer Fabrication Process  
 Assembly Process                      Means of identifying material:  
 Equipment                      CEMOS 8:                      Y-Step                      Date Code: Yyyww  
 Material                      CEMOS 11.5:                      X-Step                      Date Code: XByyww  
 Testing  
 Manufacturing Site                      yy: Year  
 Data Sheet                      ww: Work Week  
 Other

**RELIABILITY/QUALIFICATION SUMMARY:**

Please see attachment for qualification summary

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.  
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: \_\_\_\_\_  **Approval for shipments prior to effective date.**  
 Name/Date: \_\_\_\_\_ E-Mail Address: \_\_\_\_\_  
 Title: \_\_\_\_\_ Phone# /Fax# : \_\_\_\_\_

**CUSTOMER COMMENTS:** \_\_\_\_\_  
 \_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_ DATE: \_\_\_\_\_



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### ATTACHMENT - PCN #: F0301-02

**PCN Type:** Die Shrink and Process Change

**Data Sheet Change:** None

**Detail of Change:** Die shrink and process technology change (CEMOS 8 to CEMOS 11.5) for the following products:

IDT72V2103, IDT72V2113, IDT72V36100, IDT72V36110  
IDT72V295, IDT72V2105, IDT72V2101, IDT72V2111

### Conversion Schedule (Estimated)

Samples	Available upon request
Production Shipments	7/2/2003



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### ATTACHMENT - PCN #: F0301-02

**Qualification Plan:** QFI-02-17

**Test Vehicle:** IDT72V36110

Test Description/Condition	Test Methods	SS /# Fails	Test Results
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45 / 0
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45 / 0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45 / 0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	77/0	77 / 0
Latch-Up Immunity (+ - I and V stress, + - 100mA Trigger)	EIA/JESD 78	10/0	10 / 0
ESD Human Body Model	MIL-STD-883, Method 3015	9/0	9 / 0
ESD Charge Device Model	JESD22-C101	6/0	6 / 0

#### Characterization Data:

Characterization Data is available upon request.